

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Caletka et al.

Art Unit:

Serial No.:

Dkt. No.: EN9-99-080US2

Filed:

Examiner:

Title: **PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**Preliminary Amendment**

Sir:

Kindly enter this amendment prior to initial examination

**In the Specification:**

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No. 09/438,037; filed on 11/10/1999.--

The paragraph beginning on page 7, line 14 through page 8, line 5, of the specification has been amended as follows:

Fig. 3 shows the second surface 18 of the chip carrier 14 (refer to Fig. 1) covered with a mask 26. Similarly, Fig. 4 shows the first surface 24 of the board 20 covered with a mask 28. The masks 26, 28 have elongated non-circular, oblong, oval, or elliptical openings 30 located over the conductive pads 16, 22. As illustrated in Fig. 5, the elongated openings 30 within the masks 26, 28 covering the conductive pads 16, 22, respectively, have a major axis 32 and a minor